

TLC696x0 Scan MOSFET Controller for TLC696x2/4/8

1 Features

- Operating voltage V_{CC} range: 3 V to 5.5 V
- Flexible P-MOSFET driving options:
 - Maximum driving current / sustaining voltage:
 - 30 mA / 20 V: TLC69600
 - 60 mA / 20 V: TLC69610
 - 30 mA / 50 V: TLC69650
 - 60 mA / 50 V: TLC69660
 - Global 8-bit Maximum Current (MC) setting
 - Individual 8-bit Channel Current (CC) setting
- High speed daisy chain interface:
 - I/O voltage compatible with: 1.8 V / 3.3 V
 - Data transfer rate: up to 20 MHz
- EMI enhancement:
 - Programmable interface driving capability
- Display quality improvement:
 - Minimum brightness update latency
 - Programmable black insertion
 - Variable refresh rate (VRR) without flickering
- Diagnostics:
 - Device thermal shutdown detection
 - Report interface option:
 - UART and interrupt pin (INT)
 - Two-wire output: CLK_O and SOUT

2 Applications

- LCD local dimming backlight:
 - TV
 - Monitor
 - Notebook
 - Tablet

3 Description

TLC696x0 is a scan MOSFET controller compatible with current-sink driver TLC696x2/4/8 to achieve 2/4/8 time-multiplexing control. Each device integrates with 16 constant current sinks for up to 8 scan MOSFETs control. The device equips with ghost-cancellation function to eliminate upside ghosting.

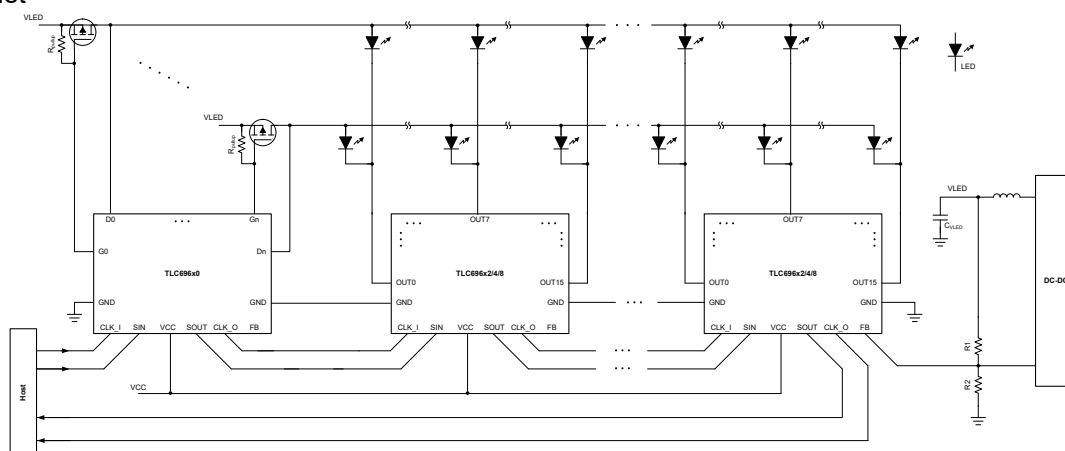
To optimize system efficiency, the device equips with adaptive headroom voltage control scheme to directly control DC/DC. Only the FB pin from last device in serial chain should be connected to DC/DC to achieve simplified system layout. The device also integrates minimum brightness update latency, black insertion and VRR features to improve display quality.

TLC696x0 has three error flags: LED open detection (LOD), LED short detection (LSD) and thermal shutdown detection (TSD) for diagnostic. The device implements two options for readback including UART/INT and SOUT/CLK_O which is programmable by register.

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
TLC696x0	DSBGA (24)	1.58 mm × 2.43 mm
	WQFN (24)	4 mm × 4 mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
April 2023	*	Initial Release

5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

[TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC69600RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69600	Samples
TLC69600YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69600	Samples
TLC69610RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69610	Samples
TLC69610YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69610	Samples
TLC69650RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69650	Samples
TLC69650YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69650	Samples
TLC69660RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69660	Samples
TLC69660YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69618	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TLC69600, TLC69610, TLC69650, TLC69660 :

- Automotive : [TLC69600-Q1](#), [TLC69610-Q1](#), [TLC69650-Q1](#), [TLC69660-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE OUTLINE

WQFN - 0.8 mm max height

The drawing illustrates the mechanical specifications of a 24-pin micro connector. It includes three views: a top view, a side view, and a detail view of the pin index area.

Top View: The connector has a square footprint with a side length of 4.15 mm (3.85 mm). The pin 1 index area is indicated by a shaded square. The pin 1 ID (optional) is shown as a small square. The exposed thermal pad is a central square with a side length of 2.45 ± 0.1 mm. The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm). The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm). The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm).

Side View: The connector has a maximum height of 0.8 mm. The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm). The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm). The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm).

Detail View: The detail view shows the pin 1 ID (optional) and the exposed thermal pad. The pin 1 ID (optional) is a small square with a side length of 0.1 mm (0.05 mm). The exposed thermal pad is a central square with a side length of 2.45 ± 0.1 mm.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

WQFN - 0.8 mm max height

24X (0.6)

24X (0.24)

SYM

20X (0.5)

(R0.05) TYP

(Ø0.2) TYP VIA

2.45

3.8

13

18

12

7

25

1

6

0.07 MAX ALL AROUND

METAL

SOLDER MASK OPENING

NON SOLDER MASK DEFINED (PREFERRED)

0.07 MIN ALL AROUND

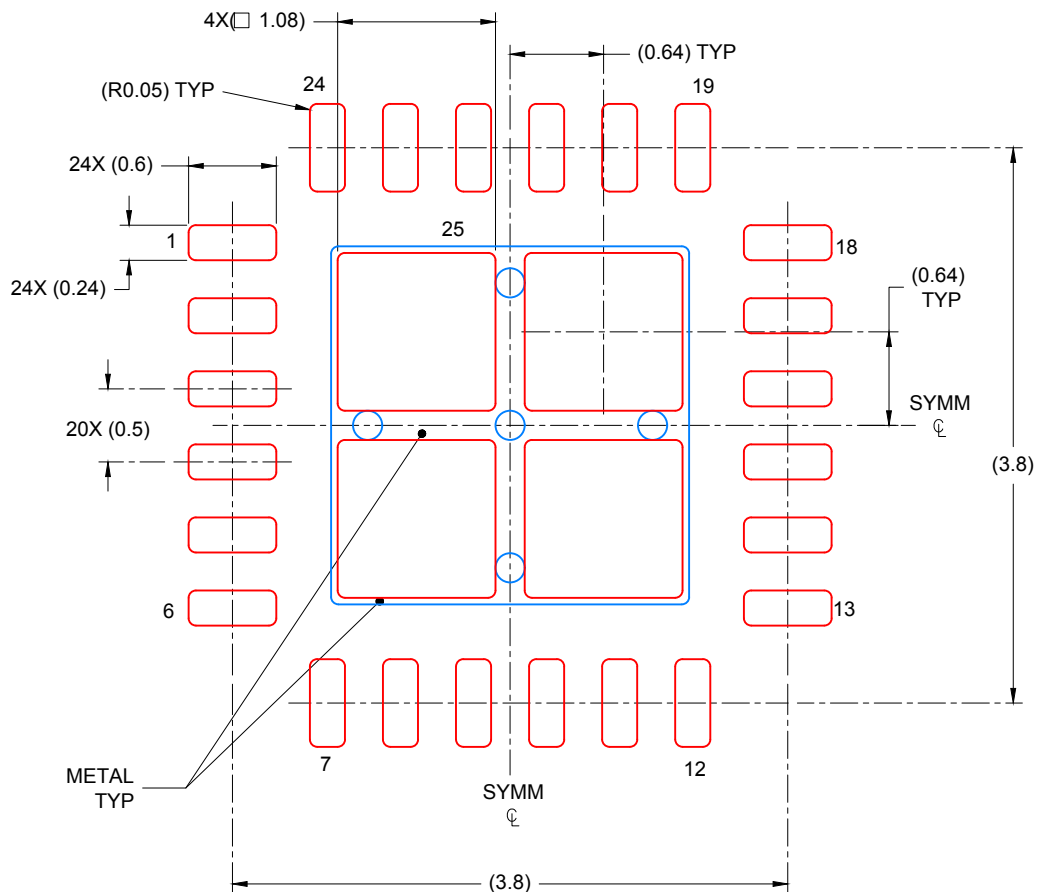
SOLDER MASK OPENING

METAL UNDER SOLDER MASK

SOLDER MASK DEFINED

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3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sl原因271).



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:
 78% PRINTED COVERAGE BY AREA UNDER PACKAGE
 SCALE: 20X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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